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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOCTITE C 502

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PRODUCT DESCRIPTION

LOCTITE C 502 provides the following product characteristics:

Technology	Solder wire - Cored
Activity	Medium
Product Benefits	<ul style="list-style-type: none">• No clean• Clear residue• Good wetting• Fast soldering• Mild odor• Pb-free and SnPb alloys available
IPC/J-STD-004 Classification	ROM1
Application	Soldering
Surface Finishes	Copper, Brass and Nickel

LOCTITE C 502 cored solder wire has been specially formulated to complement no clean wave and reflow soldering processes. LOCTITE C 502 is also well suited for soldering applications requiring high melting temperature alloys.

TYPICAL PROPERTIES

Solder Cored Wire

Alloys - Tin/lead	<ul style="list-style-type: none">• SN63• SN60• SN62
Alloys - Lead Free	<ul style="list-style-type: none">• 96SC (SAC387)• 97SC (SAC305)• 99C (SnCu)• 95A (SnSb)• 96S (SnAg)
Acid Value	156 to 172 mg KOH/g
Halide content	0.2%
Flux Content (%)	2.7

ALLOYS:

The alloys used in LOCTITE C 502 cored solder wires conform to the purity requirements of the common national and international standards.

FLUX:

LOCTITE C 502 solid flux is based on modified rosin and carefully selected activators. In practice they exhibit a mild rosin odor and leave a small quantity of clear residue.

DIRECTIONS FOR USE

Soldering with LOCTITE C 502 does not require any special methods or deviation from standard hand soldering practices.

Soldering Iron:

- Good results can be obtained using a range of tip temperatures. However, the optimum tip temperature and heat capacity required for a hand-soldering process is a function of both soldering iron design and the nature of the task.
- Care should be exercised to avoid unnecessarily high tip temperatures for extensive periods of time.
- A high tip temperature may increase any tendency to flux spitting and it may produce some residue darkening.
- The tip of the soldering iron should be properly tinned. Severely contaminated soldering iron tips should be cleaned with Multicore® Tip Tinner/Cleaner.
- Wipe the tip on a clean, damp sponge before re-tinning with LOCTITE C 502 wire.

Soldering Process:

1. Apply the soldering iron tip to the work surface. The iron tip should contact both the base material and the lead at the same time to heat both surfaces properly. It should take no more than a fraction of a second to heat both surfaces adequately.
2. Apply LOCTITE C 502 flux cored wire to a part of the joint surface away from the soldering iron and allow to form a joint fillet. This will be virtually instantaneous. Do not apply excessive solder to the joint as this will not improve joint integrity and it will leave excess flux residues on the surface.
3. Remove solder from the work piece and then remove the iron tip.
4. The total process will be very rapid, depending upon thermal mass, tip temperature, tip configuration and the solderability of the surfaces to be joined.
5. The resin and flux systems are designed to leave relatively low residues and to minimize residual activity. This is achieved by ensuring some decomposition and volatilization takes place during the soldering process

Cleaning:

LOCTITE C 502 flux cored solder wire has been formulated to leave amber flux residues and resist spitting and fuming. In most industrial and consumer electronics applications, cleaning will not be required. The product may, therefore, be used to complement a no-clean wave soldering or reflow process or to allow repairs to cleaned boards without the need for a second cleaning process. In high-reliability applications, the residues should be removed.

Should cleaning be required, this is best achieved using SC-01™ cleaner.

RELIABILITY PROPERTIES

J-STD-004	Solder spread mm ²	310
	Corrosion Test	Pass
SIR (without cleaning)	IPC-SF-818 Class 3	Pass
	Bellcore TR-NWT-000078	Pass
Electromigration (without cleaning)	Bellcore TR-NWT-000078	Pass
Classification	EN29454-1	1.1.2
	IPC-SF-818	MR3CN
	J-STD-004	ROM1

PACKAGING

LOCTITE C 502 is available in various diameters, flux percentages, and reel sizes.

DATA RANGES

The data contained herein may be reported as a typical value and/or a range. Values are based on actual test data and are verified on a periodic basis.

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Not for Product Specifications

The technical information contained herein is intended for reference only. Please contact Henkel Technologies Technical Service for assistance and recommendations on specifications for this product.

Conversions

(°C x 1.8) + 32 = °F

kV/mm x 25.4 = V/mil

mm / 25.4 = inches

µm / 25.4 = mil

N x 0.225 = lb

N/mm x 5.71 = lb/in

N/mm² x 145 = psi

MPa x 145 = psi

N·m x 8.851 = lb·in

N·m x 0.738 = lb·ft

N·mm x 0.142 = oz·in

mPa·s = cP

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The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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Americas
+1.888.943.6535

Europe
+32.1457.5611

Asia
+86.21.3898.4800

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